PN312C, PN312D

Si PIN Dual Photodiodes

Optical Information Systems

■ Features

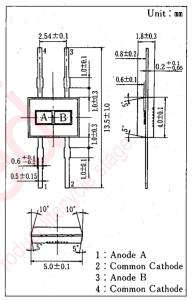
- Fast response: t_r, t_f=10ns (typ.)
- Good linearity of photo current
- Low dark current: I_D=20nA (max.)
- Small package (Flat type)
- PN312C: Clear plastic package
- PN312D: Using plastic package to cut-off visible light

■ Application

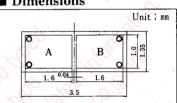
- Auto focus, distance measuring system of still and video camera
- Position sensor of automatic assembly line
- · Eye of industrial robot

■ Absolute Maximum Ratings (Ta=25°C)

Item	Symbol	Value	Unit		
Reverse Voltage (DC)	V _R	30	V		
Power Dissipation	P _D	30.	mW		
Operating Ambient Temperature	T_{opr}	-25~+85	°C		
Storage Temperature	T _{stg}	$-30 \sim +100$, (C)		



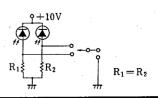
Dimensions



■ Electro-Optical Characteristics (Ta=25°C)

Item	Symbol	Condition	min.	typ.	max.	Unit	
Reverse Voltage (DC)	V _R	$I_R = 10 \mu\text{A}$	U. V	30	0		V
Dark Current	$I_{\mathbf{D}}$	$V_R = 10 \text{ V}$	2 //	.00		20	nA
Photo Current	I _L *3	$V_R = 10 V$	PN312C	10	15	,	μA
		$L = 1000 lx^{*1}$	PN312D	. 8	12		
		$V_R = 10 \text{V}, \ \lambda = 900 \text{nm},$	PN312C		10		μΑ
		$E = 1 \text{mW/cm}^2$	PN312D		9		
Peak Sensitivity Wavelength λ_P		$V_R = 10 V$	PN312C		900		nm
	Λp		PN312D		940		
Response Time	t _r , t _f *2	$V_R = 10 V$, $R_L = 1 k\Omega$		10		ns	
Capacitance between Terminals	Ct	$V_R = 10 \mathrm{V}, f = 1 \mathrm{MHz}$			5		pF
Acceptance Half Angle	θ	Measured from the optical axis to the half power point			65		deg.

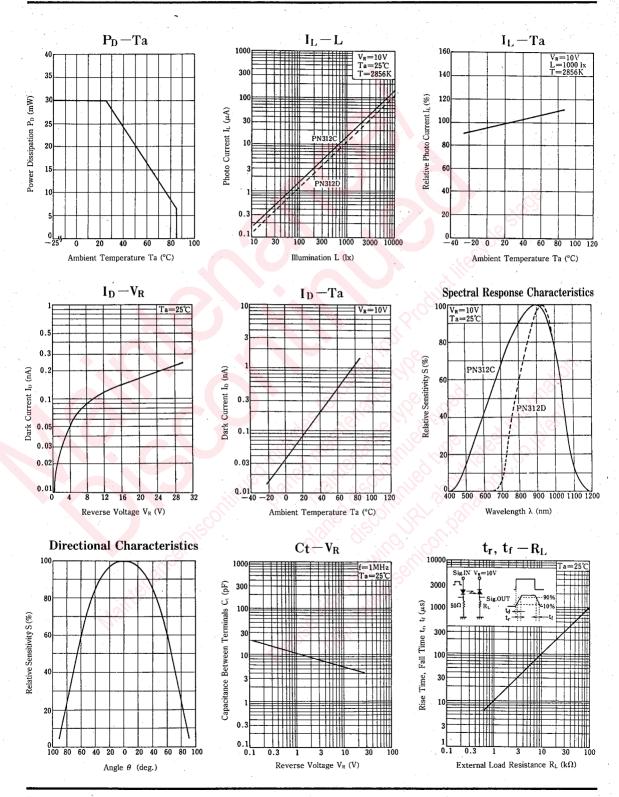
Note) Maximum Ratings and Characteristics are specified per each element.



^{*1} Source: Tungsten 2856K

^{*2} Source: Laser Diode λ=800 mm

^{*3} Photo Current Measuring Circuit



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